2.15X1.7mm SMD LED WITH CERAMIC SUBSTRATE



ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Features

- Dimension: 2.15mmX 1.7mm X 0.8mm.
- Low thermal resistance.
- Ceramic package with silicone resin.
- Higher brightness LED flash.
- Small package with high efficiency.
- Surface mount technology.
- ESD protection.
- Radiation patterns optimal for camera flash.
- Enables higher resolution pictures in darken environments.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 2a.
- Soldering methods: IR reflow soldering.
- RoHS compliant.



Application Note

Static electricity and surge damage the LEDs.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Typical Applications

Digital still cameras. Camera-phones. PDAs. Room lighting. Architectural lighting.

Decorative/pathway lighting.

Front panel backlight.

Package Dimensions



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Absolute Maximum Ratings at T_A=25°C

Parameter	Symbol	Value	Unit
Operating Temperature	erating Temperature Top		°C
Storage Temperature	Tstg	-40 To +110	°C
Junction temperature[1]	TJ	110	°C
DC Forward Current [1]	lF	150	mA
Peak Forward Current [2]	IFM	300	mA
Reverse Voltage	VR	5	V
Power dissipation	PD	0.6	W
Electrostatic Discharge Threshold (HBM)		8000	V
Thermal resistance [1] (Junction/ambient)	Rth j-a	170	°C/W
Thermal resistance [1] (Junction/solder point)	Rth j-s	55	°C/W

Notes:

1. Results from mounting on PC board FR4, mounted on pc board-metal core PCB is recommend

for lowest thermal resistance. 2. 1/10 Duty Cycle, 0.1ms Pulse Width.

Electrical / Optical Characteristics at TA=25°C

Parameter	Symbol	Value		Unit
Forward Voltage IF = 150mA [Min.]		2.7	V	
Forward Voltage IF = 150mA [Typ.]	VF [1]	3.5		
Forward Voltage IF = 150mA [Max.]		4.0		
Reverse Current	Ir	lr 10		μΑ
	η opt	AT2117QR425ZS-VFS-C1	62.86	
Optical efficiency		AT2117QR425ZS-VFS-N1	55.24	
		AT2117QR425ZS-VFS-N2	59.05	1 0.07
		AT2117QR425ZS-VFS-W1	47.62	Im/vv
		AT2117QR425ZS-VFS-W2	49.52	
		AT2117QR425ZS-VFS-W3	51.43	
Temperature coefficient of x IF = 150mA, -10 $^{\circ}$ C \leq T \leq 100 $^{\circ}$ C [Typ.]	TC x	-0.15		10 ⁻³ /° C
$\label{eq:linear} \begin{array}{c} \mbox{Temperature coefficient of y} \\ \mbox{IF} = 150 \mbox{mA}, \mbox{-}10 \ ^{\circ} \ \mbox{C} \leq T \leq 100 \ ^{\circ} \ \mbox{C} \ \ \mbox{[Typ.]} \end{array}$	ТСу	-0.13		10 ⁻³ /° C
$\label{eq:IF} \begin{array}{c} \mbox{Temperature coefficient of } VF \\ \mbox{IF} = 150 \mbox{mA}, \mbox{-}10 \ ^{\circ} \ C \ \leq T \leq 100 \ ^{\circ} \ C \ \mbox{[Typ.]} \end{array}$	ΤCv	-3.1		mV/° C

Note:

1. Forward voltage is measured with a current pulse of 10ms at a tolerance of $\pm 0.1V$.

Selection Guide

Part No. Color		CCT Range (K)		Lens Type	Luminous Intensity [2] Iv(cd)@ 150mA		Φν (lm) [3] @ 150mA	Viewing Angle [1]	
		Min.	Тур.	Max.		Min.	Тур.	Тур.	201/2
AT2117QR425ZS-VFS-C1	Cool White	5310	6000	7040	WATER CLEAR	5.7	8.3	33	120 °
AT2117QR425ZS-VFS-N1	Neutral White	3710	4000	4260	WATER CLEAR	4.7	7.7	29	120 °
AT2117QR425ZS-VFS-N2	Neutral White	4260	4700	5310	WATER CLEAR	5.7	8.0	31	120 °
AT2117QR425ZS-VFS-W1	Warm White	2580	2700	2870	WATER CLEAR	3.8	6.7	25	120 °
AT2117QR425ZS-VFS-W2	Warm White	2870	3000	3220	WATER CLEAR	3.8	7	26	120 °
AT2117QR425ZS-VFS-W3	Warm White	3220	3500	3710	WATER CLEAR	4.7	7.5	27	120 °

Brightness codes

ERP	Part No	lum	Φν (lm) [3] @ 150mA		
		Code.	Min.	Max.	Тур.
		ZE	5.7	7.5	24
1010000010		ZF	6.7	8.5	30
1212000212 AI	A12117QR42525-VF5-C1	ZG	7.5	10	35
		ZH	8	12	40
		ZD	4.7	6.5	20
4040000040		ZE	5.7	7.5	25
1212000213	A12117QR42525-VF5-N1	ZF	6.7	8.5	30
		ZG	7.5	10	35
		ZE	5.7	7.5	24
1212000214 AT2117QF		ZF	6.7	8.5	30
	A12117QR42525-VF5-N2	ZG	7.5	10	35
		ZH	8	12	38
1212000215 AT2117Q		ZC	3.8	5.5	17
		ZD	4.7	6.5	25
	A12117QR42525-VF5-W1	ZE	5.7	7.5	30
		ZF	6.7	8.5	35
1212000216 AT2117QR425Z	AT2117QR425ZS-VFS-W2	ZC	3.8	5.5	17
		ZD	4.7	6.5	25
		ZE	5.7	7.5	30
		ZF	6.7	8.5	35
1212000217		ZD	4.7	6.5	20
	AT2117QR425ZS-VFS-W3	ZE	5.7	7.5	25
		ZF	6.7	8.5	30
		ZG	7.5	10	35

Notes:

1.0 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2.Luminous intensity is measured by a current pulse of 10ms at a tolerance of ±15%.
3.The typical data of Luminous Flux can only reflect statistical figures, actual parameters of individual product could differ from the typical data.

For the purpose of product enhancement, the typical data is subject to change without prior notice.

Shipment may contain more than one of the light intensity groups. Orders for single light intensity group are generally not accepted.



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Forward Voltage Groups

	11	
Min.	Max.	Unit
2.7	2.9	V
2.9	3.1	V
3.1	3.3	V
3.3	3.6	V
3.6	3.9	V
3.9	4.1	V

Notes:

Forward voltage is measured with a current pulse of 10ms at a tolerance of $\pm 0.1V$.

Shipment may contain more than one of the forward voltage groups. Orders for single forward voltage group are generally not accepted.









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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.



Heat Generation:

1. Thermal design of the end product is of paramount importance. Please consider the heat generation of the LED when making the system design. The coefficient of temperature increase per input electric power is affected by the thermal resistance of the circuit board and density of LED placement on the board ,as well as other components. It is necessary to avoid intense heat generation and operate within the maximum ratings given in this specification.

2.Please determine the operating current with consideration of the ambient temperature local to the LED and refer to the plot of Permissible Forward current vs. Ambient temperature on CHARACTERISTICS in this specification. Please also take measures to remove heat from the area near the LED to improve the operational characteristics on the LED.

3. The equation \bigcirc indicates correlation between T_j and T_a ,and the equation \oslash indicates correlation between T_j and T_s

$T_j = Ta + Rthj-a *W \dots $	
$Tj = Ts + Rthj-s *W \qquad (2)$	
Tj = dice junction temperature: °C	
Ta = ambient temperature:°C	
Ts = solder point temperature:°C	
Rthj-a = heat resistance from dice j	unction temperature to ambient temperature : °C / W
Rthj-s = heat resistance from dice j	unction temperature to Ts measuring point : $^\circ C$ / W
W = inputting power (IFx VF) : W	



Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might leads to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.



2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.





3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
- 5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.

